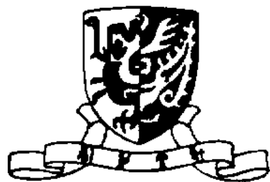

THE CHINESE UNIVERSITY OF HONG KONG
DEPARTMENT OF ELECTRONIC ENGG
Micro and Nano Fabrication Laboratory
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LIST OF CHARGES – Aug 2012
Charges for Using Equipment/Instruments

Equipment/ Instrument	Industry or Government Rate		Institutions	
	Equipment Charge (HK$/Hourly Rate)	Operator Charge [1] (HK$/Hourly Rate)	Equipment Charge (HK$/Hourly Rate)	Operator Charge [1] (HK$/Hourly Rate)
Electron Beam Lithography (EBL) [1]	500	380	400	380
ICP Silicon dry etcher	720		500	
Plasma Enhanced Chemical Vapour Deposition (PECVD)	500		350	
Low Pressure Chemical Vapour Deposition (LPCVD)	500		350	
Photolithography, without aligner	500		350	
Photolithography, aligner [3]	700		500	
Plasma Etching	330		250	
Thin Film Deposition –sputtering [4]	300		210	
Thin Film Deposition –e-beam [4]	300		210	
High Temperature furnace	220		150	
Rapid temperature annealing	220		150	
Vacuum Annealing	220		150	
CleanRoom usage [2]	450/4hours	/	350/4hours	/

[1] Operator charges are only applicable if the end user requests help because he is not qualified to operate equipment. This charge is not applicable if technical support is not needed to operate the machine.
[2] Clean room usage charges is set by the clean room management committee and is applicable to users from outside CUHK Faculty of Engineering: it covers the cost associated with using facility (e.g. use of clean room garments, user of wet benches for resist processing, chemical waste disposal, optical microscopes for inspection, disposal face masks and gloves etc).
[3] Minimum 0.5hours
[4] User also need to pay the target material cost, e.g., gold.
All equipment except EBL, CU user will be discount to 70% of institutions price

MMW Engineering Bldg., CUHK, ShaTin, N.T., HONG KONG